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(54) Title: SYSTEM AND METHOD FOR BONDED CONFIGURATION PAD CONTINUITY CHECK

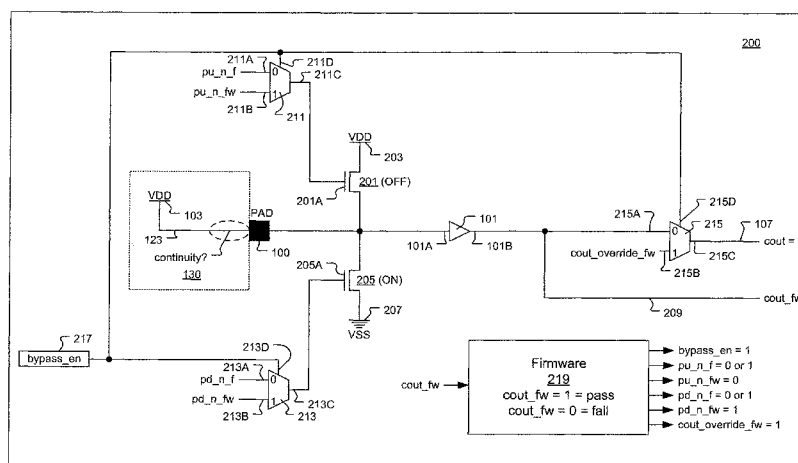


Fig. 2A

(57) Abstract: A continuity test circuit for a boundary pad includes a pull-up transistor electrically connected between the boundary pad and a first power supply, and a pull-down transistor electrically connected between the boundary pad and a first reference ground potential. A normal output conductor is electrically connected to have a same electrical state as the boundary pad during normal operation. A continuity test output conductor is electrically connected to have a same electrical state as the boundary pad during continuity test operation. Continuity testing control circuitry is defined to control the pull-up transistor, the pull-down transistor, and the normal output conductor during continuity test operation such that an electrical state present on the continuity test output conductor indicates a status of electrical continuity between the boundary pad and either a second power supply or a second reference ground potential to which the boundary pad should be electrically connected.